

**Abstract**

First and second mounds of dielectric respectively encapsulate first and second conductors. A third dielectric fills a valley between the first and second mounds of dielectric, and encapsulates a third conductor. A first  
5 ground shield is deposited on at least sides of the first and second mounds of dielectric, abutting the third dielectric. Second and third ground shields may run above and below the conductors. In this manner, first, second and third transmission lines are formed.